

WHAT IS CLAIMED IS:

1. An envelope, comprising:
a first substrate;
a second substrate opposed to the first
5 substrate;
a frame interposed between the first substrate
and the second substrate; and
a low melting point metal for bonding the first
substrate and the frame to each other,
10 wherein the first substrate has a first region
and a second region which are brought into contact
with the low melting point metal, and in the first
region, a material capable of higher maintaining
airtightness with the low melting point metal than
15 the second region is in contact with the low melting
point metal, while in the second region, a material
having a stronger binding power on the low melting
point metal than the first region is in contact with
the low melting point metal.

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2. An envelope, comprising:
a first substrate;
a second substrate opposed to the first
substrate;
25 a frame interposed between the first substrate
and the second substrate; and
a low melting point metal for bonding the first

substrate and the frame to each other,
wherein the frame has a first region and a
second region which are brought into contact with the
low melting point metal, and in the first region, a
5 material capable of higher maintaining airtightness
with the low melting point metal than the second
region is in contact with the low melting point metal,
while in the second region, a material having a
stronger binding power on the low melting point metal
10 than the first region is in contact with the low
melting point metal.

3. A method for manufacturing an envelope, the
method comprising steps of:

15 preparing a first substrate, a second substrate
opposed to the first substrate, and a frame
interposed between the first substrate and the second
substrate; and
bonding the first substrate and the frame to
20 each other with a low melting point metal,
wherein, in the bonding step, used as the first
substrate is a substrate that: has a first region and
a second region which are brought into contact with
the low melting point metal; in the first region, is
25 capable of higher maintaining airtightness with the
low melting point metal than in the second region;
and in the second region, has a stronger binding

power on the low melting point metal than in the first region.

4. A method for manufacturing an envelope, the
5 method comprising steps of:

preparing a first substrate, a second substrate opposed to the first substrate, and a frame interposed between the first substrate and the second substrate; and

10 bonding the first substrate and the frame to each other with a low melting point metal,

wherein, in the bonding step, used as the frame is a frame that: has a first region and a second region which are brought into contact with the low 15 melting point metal; in the first region, is capable of higher maintaining airtightness with the low melting point metal than in the second region; and in the second region, has a stronger binding power on the low melting point metal than in the first region.

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5. An image display device, comprising:
the envelope according to claim 1; and
a display element placed in the envelope.

25 6. An image display device, comprising:
the envelope according to claim 2; and
a display element placed in the envelope.

7. A television display device, comprising:
an image display device having the envelope
according to claim 1 and a display element placed in
the envelope,

5 wherein the image display device receives a
television signal.

8. A television display device, comprising:
an image display device having the envelope
10 according to claim 2 and a display element placed in
the envelope,

 wherein the image display device receives a
television signal.